Form 1449 (Modified)	Atty Docket No NSC1P296/P05887	Application No.: NEW
Information Disclosure	Applicant:	
Statement By Applicant	Soon et al.	
	Filing Date	Group
(Use Several Sheets if Necessary)	HEREWITH	UNASSIGNED

U.S. Patent and Published Documents

Examiner						Sub-	Filing
Initial	No.	Patent No.	Date	Patentee	Class	class	Date
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Foreign Patent or Published Foreign Patent Application

Examiner	T	Document	Publication	Country or		Sub-	Trans	slation
Initial	No.	No.	Date	Patent Office	Class	class	Yes	No
	B1	WO02/08257	10/17/02	WIPO				
DW9	B2	EP0753891	1/15/97	EPO		->		

## Other Documents

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Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
DHO		John Barber, "Plastic Packaging and the Effects of Surface Mount Soldering Techniques," Microchip Technology, Inc., 12 pages, 1995
010	C2	Lai et al., Nordic Electronic Packaging Guideline, Chapter A, printed from: <a href="http://www.extra.ivf.se/mgl/A-WireBonding/ChapterA.htm">http://www.extra.ivf.se/mgl/A-WireBonding/ChapterA.htm</a> , on March 16, 2004, 25 Pages
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OWO		Nakanishi et al., "Development of High Density Memory IC Package by Stacking IC Chips," Abstract No. XP000624986, IEEE, Vol. Conf. 45, Pages 634-640 (1995)			
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Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.